# imall

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# Panasonic

MTM231232LBF

### MOS FET MTM231232LBF

## Silicon P-channel MOSFET

### For Switching

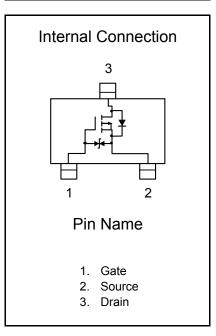
#### MTM76123 in SMini3 type package

- Features
- Low Drain-source On-state Resistance : RDS(on) typ. = 40 m $\Omega$  (VGS = -4 V)
- Low Drive Voltage : 2.5 V Drive
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL : Level 1 compliant)
- Marking Symbol : BL

#### Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

	Unit : mm		
2.0 0.3 3 1 (0.65)(0.6 1.3			
	1. Gate 2. Source 3. Drain		
Panasonic	SMini3-G1-B		
JEITA	SC-70		
Code	SOT-323		



#### ■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit				
Drain to Source Voltage	VDS	-20	V				
Gate to Source Voltage	VGS ±10		V				
Drain Current	ID	-3	А				
Drain Current (Pulsed) *1	IDp	-16	А				
Total Power Dissipation *2	PD	500	mW				
Channel Temperature	Tch	150	°C				
Storage Temperature Range	Tstg	-55 to +150	О°				

Note \*1 Pulse width  $\leq$  10  $\mu$ s, Duty cycle  $\leq$  1 %

\*2 Measuring on ceramic board at 40 mm  $\times$  38 mm  $\times$  0.1 mm. Absolute maximum rating PD Non-heat sink shall be made 150 mW.

# **Panasonic**

### MOS FET MTM231232LBF

■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source Breakdown Voltage	VDSS	ID = -1 mA, VGS = 0 V	-20			V
Zero Gate Voltage Drain Current	IDSS	VDS = -20 V, VGS = 0 V			-1	μA
Gate-source Leakage Current	IGSS	VGS = ±8 V, VDS = 0 V			±10	μA
Gate-source Threshold Voltage	Vth	ID = -1 mA, VDS = -10 V	-0.4	-0.85	-1.3	V
Drain-source On-state Resistance *1	RDS(on)1	ID = -1 A, VGS = -4 V		40	55	mΩ
	RDS(on)2	ID = -0.5 A, VGS = -2.5 V		45	70	
Forward transfer admittance *1	Yfs	ID = -1 A, VDS = -10 V, f = 1 kHz	3.5			S
Input Capacitance	Ciss	VDS = 10 V VCS = 0 V		1 000		pF
Output Capacitance	Coss	VDS = -10 V, VGS = 0 V f = 1 MHz		120		
Reverse Transfer Capacitance	Crss			120		
Turn-on Delay Time *2	td(on)	VDD = -10 V, VGS = 0 to -4 V		25		ns
Rise Time *2	tr	ID = -1 A		25		
Turn-off Delay Time <sup>*2</sup>	td(off)	VDD = -10 V, VGS = -4 to 0 V		120		
Fall Time <sup>*2</sup>	tf	ID = -1 A		70		ns

Note : Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

\*1 Pulse test : Pulse width  $\leq$  300  $\mu s,$  Duty cycle  $\leq$  2 %

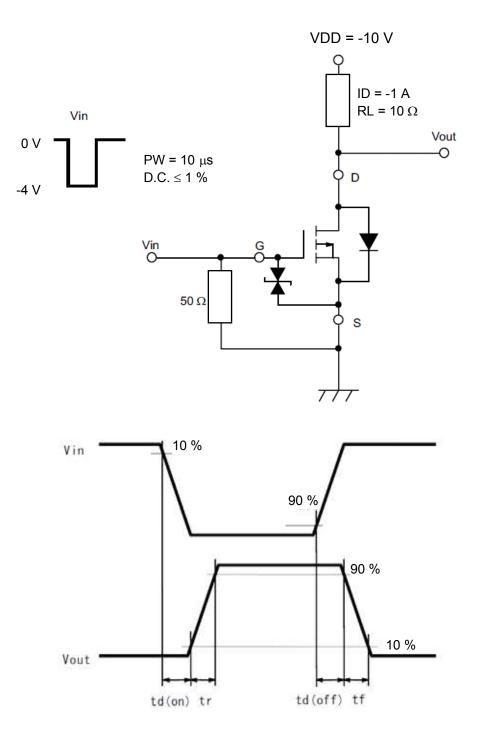
\*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time

Doc No. TT4-EA-14177 Revision. 2



MOS FET MTM231232LBF

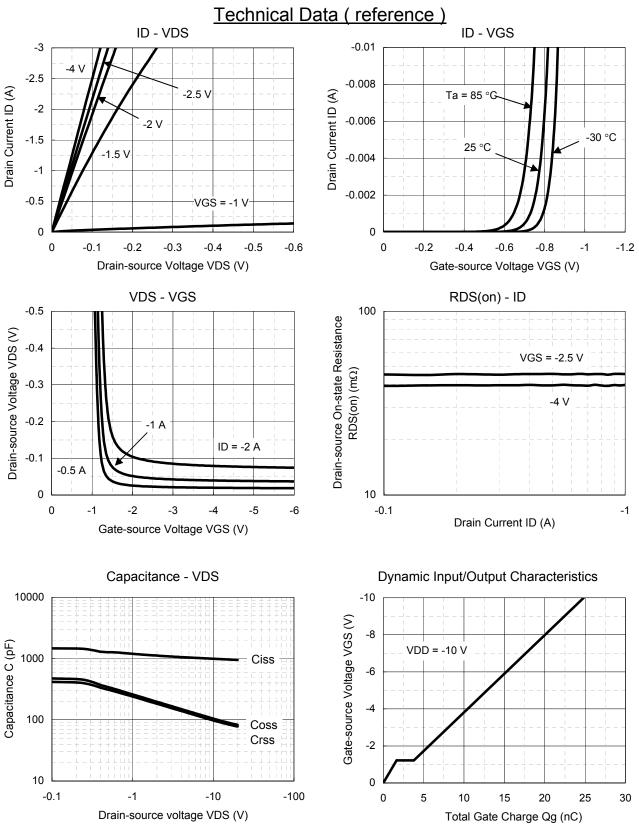
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Established : 2012-04-21 Revised : 2013-03-07



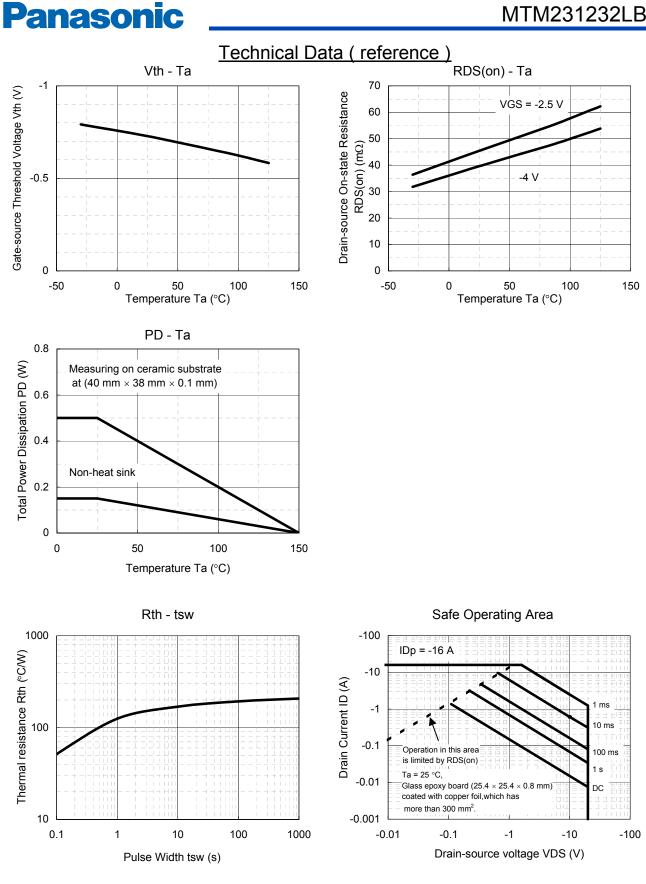
MOS FET MTM231232LBF



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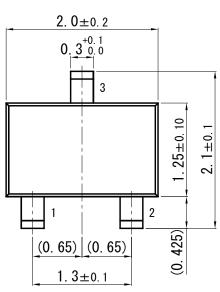
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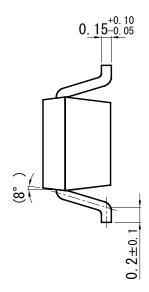


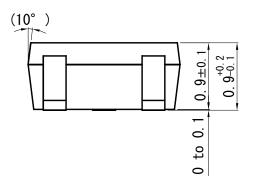
MOS FET MTM231232LBF

Unit : mm

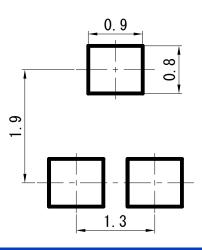
## SMini3-G1-B







Land Pattern (Reference) (Unit : mm)



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